

170- μ Vrms ZERO-RIPPLE SWITCHED CAP BUCK-BOOST CONVERTER FOR VCO SUPPLY

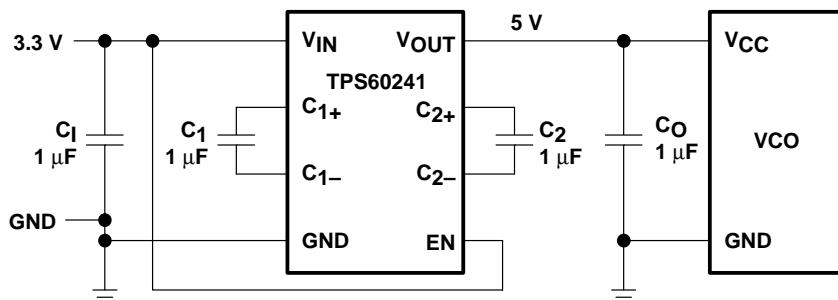
FEATURES

- Wide Input Voltage Range:
 - 1.8 V To 5.5 V for 2.7-V, 3-V, 3.3-V Output (TPS60240/2/3)
 - 2.7 V To 5.5 V for 5-V Output (TPS60241)
- 170- μ Vrms Zero Ripple Output:
 - at 20 Hz to 10 MHz Bandwidth
- Minimum Number of External Components
 - No Inductors
 - Only Small Ceramic Chip Capacitors
- Up to 90% Efficiency
- Regulated 3.3-V (TPS60240), 5-V (TPS60241), 3-V (TPS60243), and 2.7-V (TPS60242) Output Voltage With $\pm 2.5\%$ Accuracy Over Load
- Up to 25-mA Output Current
- Shutdown Mode: 0.1 μ A Typical
- Thermal Protection and Current Limit
- Microsmall 8-Pin MSOP Package
- EVM Available TPS60241EVM-194

APPLICATIONS

- VCO and PLL Power for:
 - PDA Phones
 - Cellular Phones
 - PCMCIA Modems
- Smartcard Readers

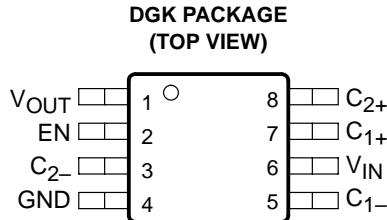
typical application circuit



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description(continued)

The devices are thermally protected and current-limited for reliable operation even under persisting fault conditions. Normal quiescent current (ground pin current) is only 250 µA, and typically 0.1 µA in shutdown mode. The TPS6024x devices come in a thin, 8-pin MSOP (DGK) package with a component height of only 1.1 mm.

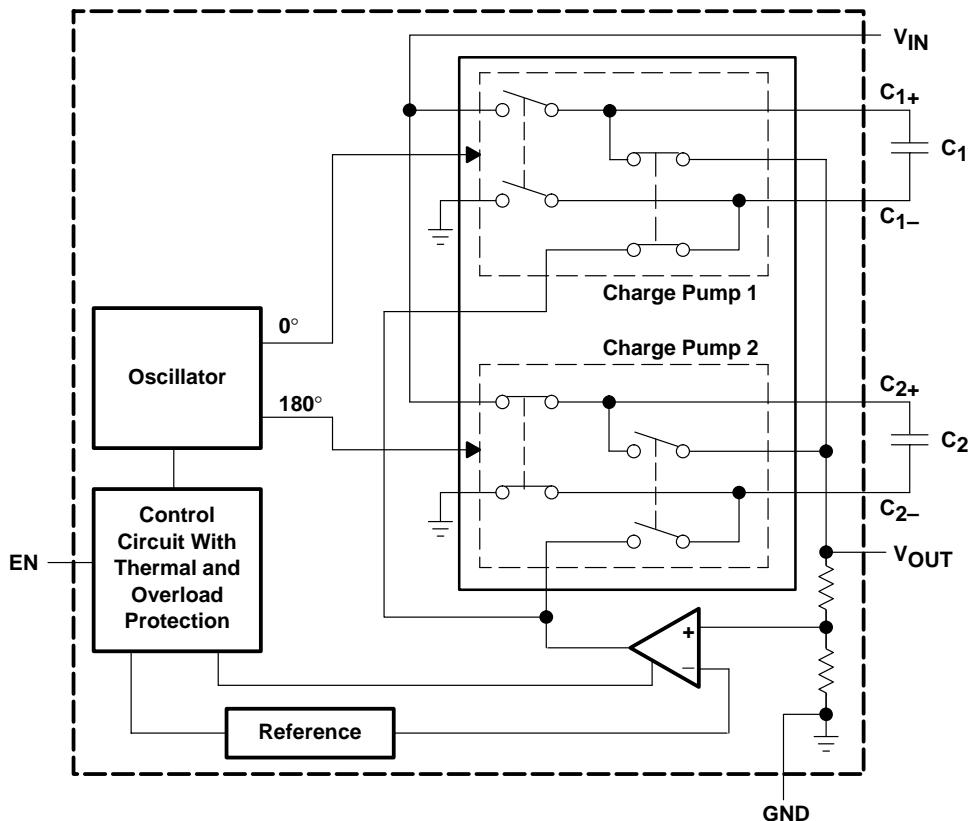


AVAILABLE OPTIONS

T _A	PART NUMBER [†]	PACKAGE MARKING	PACKAGE	OUTPUT VOLTAGE (V)
–40°C to 85°C	TPS60241DGKR	AUB	DGK (8-pin MSOP)	5 V
	TPS60240DGKR	ATM	DGK (8-pin MSOP)	3.3 V
–40°C to 85°C	TPS60242DGKR	AYF	DGK (8-pin MSOP)	2.7 V
	TPS60243DGKR	AYG	DGK (8-pin MSOP)	3 V

[†] This package type is available taped and reeled only. Quantity is 2500 units per reel (e.g., TPS60241DGKR). The devices are also available on mini reel with 250 units per reel. To order this packaging option, replace the R with a T in the part number (e.g., TPS60261DGKT).

functional block diagram



Terminal Functions

TERMINAL NAME	TERMINAL NO.	I/O	DESCRIPTION
C ₁₊	7		Positive terminal of the flying capacitor C ₁
C ₁₋	5		Negative terminal of the flying capacitor C ₁
C ₂₊	8		Positive terminal of the flying capacitor C ₂
C ₂₋	3		Negative terminal of the flying capacitor C ₂
EN	2	I	Enable terminal, active high
GND	4		Ground
V _{IN}	6	I	Supply voltage input TPS60241: 2.7 V to 5.5 V, TPS60240/2/3: 1.8 V to 5.5 V. Bypass V _{IN} to GND with a 1- μ F external capacitor (C ₁).
V _{OUT}	1	O	Regulated power output. Bypass V _{OUT} to GND with a 1- μ F external filter capacitor (C ₀). TPS60241: regulated 5-V output, TPS60240: regulated 3.3-V output, TPS60242: regulated 2.7-V output, TPS60243: regulated 3-V output

detailed description

operating principle

The TPS6024x charge pump is a fixed-frequency, dual-phase charge pump that provides 25 mA of continuous supply current for low-noise applications such as VCOs used in cell phones and wireless appliances.

Low-noise operation results from using a proprietary dual-phase charge pump topology that relies on an operational amplifier in the feedback loop to reduce ripple. During the first phase, C_1 is charged to the supply voltage. Terminal C_{1+} is connected to V_{IN} , and C_{1-} is connected to GND. In the second phase, C_{1-} is connected to the output of the operational amplifier, and C_{1+} is connected to V_{OUT} . The operational amplifier then adjusts its output until the output V_{OUT} delivers the correct voltage to make the resistor divided feedback point equal to the reference voltage. During this second phase, C_2 is charged to supply voltage. Terminal C_{2-} is connected to GND, and C_{2+} is connected to V_{IN} . Phase one is then repeated with C_2 , now acting to provide charge to the output in place of C_1 , which is connected to the supply. The dual-phase operation lowers the output ripple voltage significantly compared to a standard single-phase charge pump. In addition, the linear feedback of the operational amplifier eliminates the ripple during discharge of the output capacitor (C_O).

shutdown

Driving EN low disables the converter. This disables the internal circuits and reduces input current to typically 0.1 μ A. In this mode, the load is disconnected from the supply voltage. The device exits shutdown once EN is set to a high level.

start-up procedure

The converter is enabled when EN is set from logic low to high. The start-up time to reach 90% of the nominal output voltage is typically 0.5 ms at load currents lower than 10 mA and with an output capacitor of 1 μ F. Increasing the values of C_O delays the start-up time.

absolute maximum ratings over operating free-air temperature (unless otherwise noted)[†]

Supply voltage, V_{DD}	–0.3 V to 6 V
Power dissipation, P_D	Internally limited
Voltage EN	–0.3 V to 6 V
Voltage C_{2-} , C_{1-}	–0.3 V to V_I or 5.5 V, whichever is lowest
Voltage C_{2+} , C_{1+}	–0.3 V to V_I , V_O , or 5.5 V, whichever is lowest
Junction temperature, T_J	125°C
Storage temperature, T_{STG}	–65°C to 150°C
Shortcircuit output current	80 mA maximum

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25^\circ\text{C}$	DERATING FACTOR ABOVE $T_A = 25^\circ\text{C}$	$T_A = 70^\circ\text{C}$	$T_A = 85^\circ\text{C}$
	POWER RATING		POWER RATING	POWER RATING
DGK	376 mW	3.76 mW/ $^\circ\text{C}$	207 mW	150 mW

NOTE: The thermal resistance junction to ambient of the DGK package is $R_{TH-JA} = 150^\circ\text{C/W}$.

recommended operating conditions

		MIN	NOM	MAX	UNIT
V _I	Input voltage range	TPS60240, TPS60242, TPS60243	1.8	5.5	V
		TPS60241	2.7	5.5	
I _O	Output current range	All devices	25		mA
C _I	Input capacitor		1		μF
C ₁ , C ₂	Flying capacitors		1		μF
C _O	Output capacitor		1		μF
T _A	Operating temperature range		-40	85	°C

electrical characteristics for TPS6024X at T_A = 25°C, C_I = C_O = 1 μF, C₁ = C₂ = 1 μF (unless otherwise noted), limits apply over the specified temperature range, -40°C to 85°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT	
V _I	Input voltage	TPS60240 Assured start-up	I _O ≤ 5 mA, R _L = 600 Ω	1.8	5.5	V	
		TPS60241 Assured start-up	I _O ≤ 12 mA, R _L = 417 Ω	2.7	5.5		
		TPS60242 Assured start-up	I _O ≤ 12 mA, R _L = 225 Ω	1.8	5.5		
		TPS60243 Assured start-up	I _O ≤ 10 mA, R _L = 300 Ω	1.8	5.5		
V _O	Output voltage	TPS60240	1.8 V ≤ V _I ≤ 5.5 V, 0 mA ≤ I _O ≤ 5 mA	3.2175	3.3	3.3825	
			2.4 V ≤ V _I ≤ 5.5 V, 0 mA ≤ I _O ≤ 25 mA				
		TPS60241	2.7 V ≤ V _I ≤ 5.5 V, 0 mA ≤ I _O ≤ 12 mA	4.875	5	5.125	
			3 V ≤ V _I ≤ 5.5 V, 0 mA ≤ I _O ≤ 25 mA				
		TPS60242	1.8 V ≤ V _I ≤ 5.5 V, 0 mA ≤ I _O ≤ 12 mA	2.6325	2.7	2.7675	
			2.3 V ≤ V _I ≤ 5.5 V, 0 mA ≤ I _O ≤ 25 mA				
I _O	Output current	TPS60243	1.8 V ≤ V _I ≤ 5.5 V, 0 mA ≤ I _O ≤ 10 mA	2.925	3	3.075	
			2.3 V ≤ V _I ≤ 5.5 V, 0 mA ≤ I _O ≤ 25 mA				
		TPS60240/2/3	Nominal	2 V ≤ V _I ≤ 5.5 V	12	mA	
			Short circuit	V _I = 2 V	80		
V _n	Output noise voltage	TPS60241	Nominal	2.7 V ≤ V _I ≤ 5.5 V	12		
			Short circuit	V _I = 3.25 V	80		
f _{OSC}	Internal clock source			100	160	220	KHz
V _n	Output noise voltage	TPS60240/2/3	V _I < 2.5 V, I _O = 5 mA, ESR < 0.1 Ω, measured over 20 Hz to 10 MHz, C _O = 4.7 μF		170	μV RMS	
			V _I = 2.7 V, I _O = 5 mA, ESR < 0.1 Ω, measured over 20 Hz to 10 MHz, C _O = 4.7 μF		170		
V _{I(H)}	EN	Logic high input voltage V _{OH}		1.3	5.5	V	
V _{I(L)}	EN	Logic low input voltage V _{OL}		-0.2	0.4	V	
I _{I(H)}	EN	Logic high input current			100	nA	
I _{I(L)}	EN	Logic low input current			100	nA	
t(EN)	EN	Start-up time	V _O > 90% of V(NOM) 0.1 mA ≤ I _O ≤ 10 mA, C _O = 1 μF	0.5		ms	
η	Efficiency	TPS60240	I _O = 5 mA, V _I = 1.8 V		89.6%		
		TPS60241	I _O = 10 mA, V _I = 2.7 V		90.8%		
		TPS60242	I _O = 10 mA, V _I = 1.8 V		73%		
		TPS60243	I _O = 10 mA, V _I = 1.8 V		81%		

electrical characteristics for TPS6024X at $T_A = 25^\circ\text{C}$, $C_I = C_O = 1 \mu\text{F}$, $C_1 = C_2 = 1 \mu\text{F}$ (unless otherwise noted), limits apply over the specified temperature range, -40°C to 85°C (continued)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_Q	Quiescent current	$I_O = 0 \text{ mA}$, $V_I = 3 \text{ V}$		250	325	μA
		In shutdown mode		0.1	1	
Thermal shutdown	Temperature activated			160		$^\circ\text{C}$
	Temperature deactivated			140		

TYPICAL CHARACTERISTICS

Table of Graphs

		FIGURE	
Efficiency	vs Input voltage	1–4	
	vs Output current	5–8	
V_O	Output voltage	9–12	
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Quiescent current	vs Input voltage	18	
	vs Free-air temperature	19	
$I_{L(\text{sd})}$	Shutdown current	vs Free-air temperature	20
V_n	Output noise voltage	vs Output current	21
	Maximum output current	vs Input voltage	22–25
Load transient response		26	
Start-up timing		27	
Line transient response		28	
Noise voltage spectrum		29	
Output voltage ripple		vs Time	30

TYPICAL CHARACTERISTICS

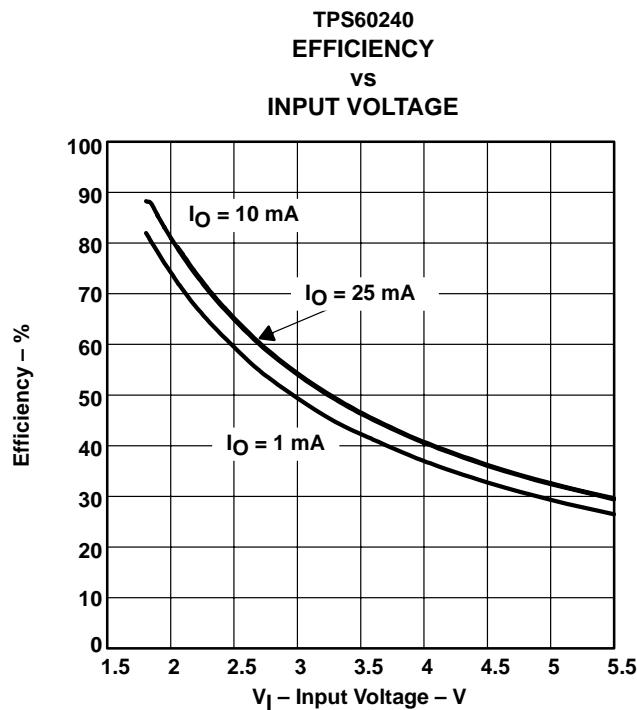


Figure 1

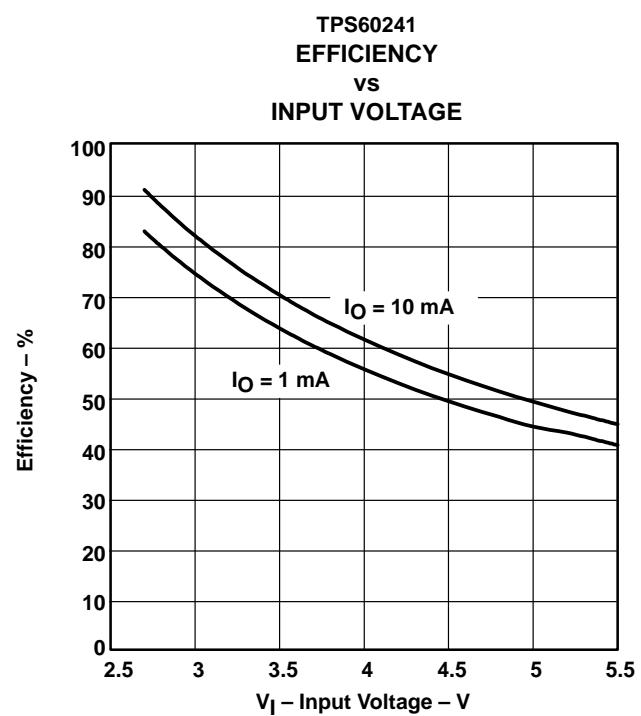


Figure 2

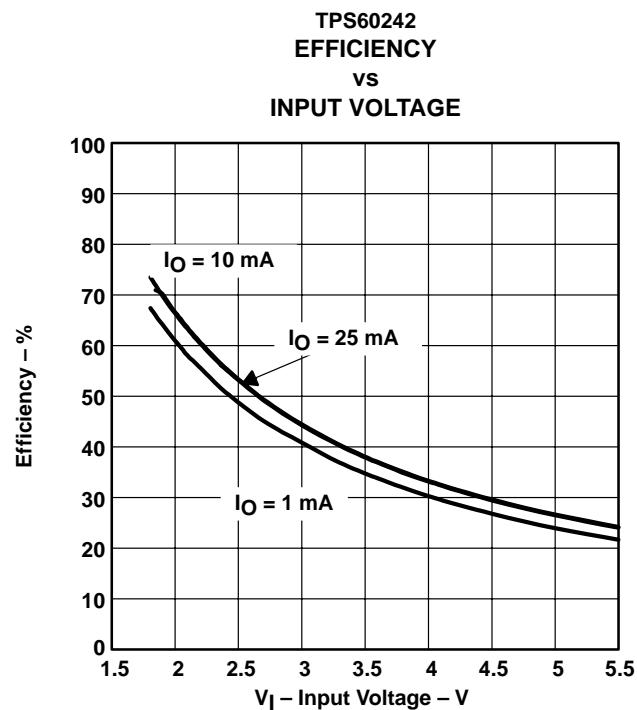


Figure 3

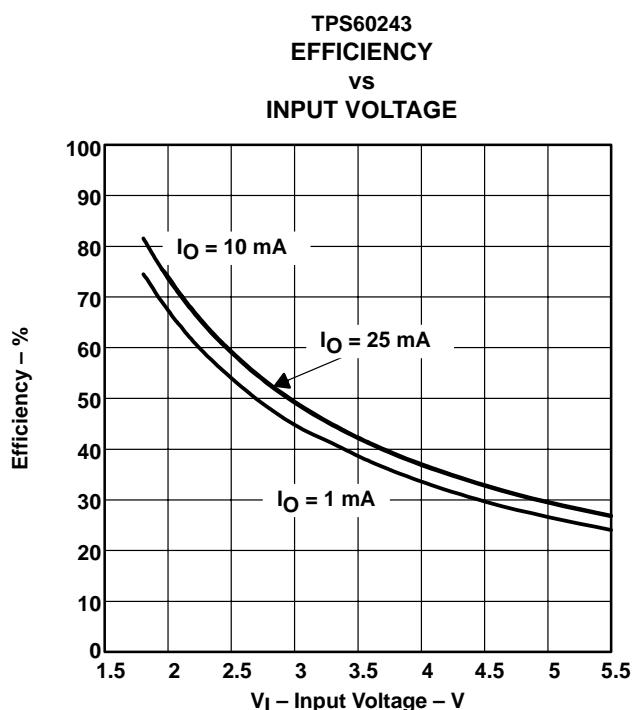


Figure 4

TYPICAL CHARACTERISTICS

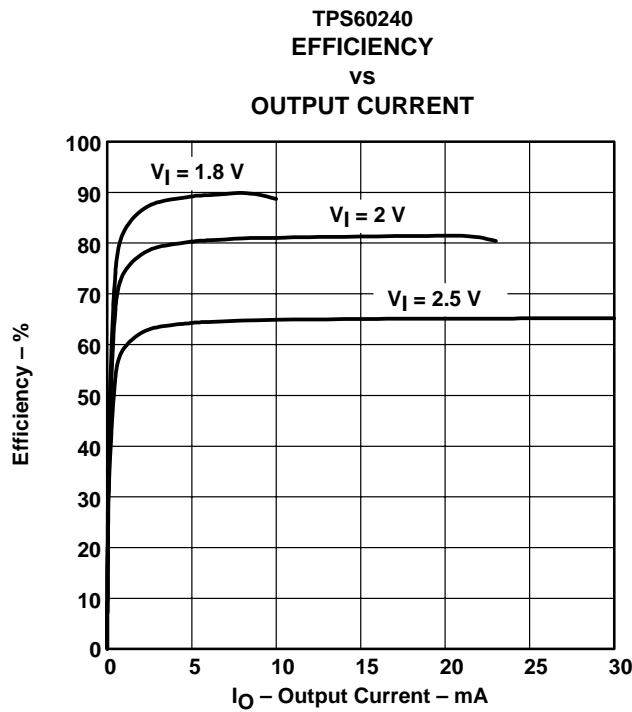


Figure 5

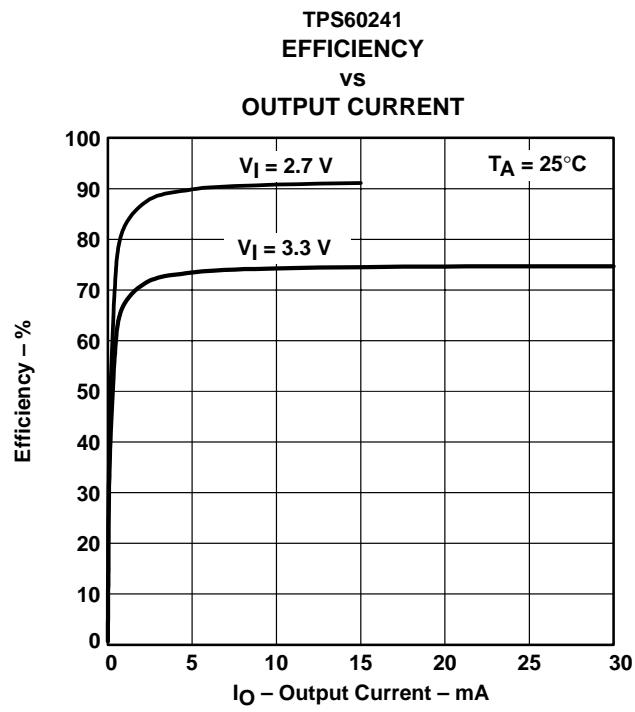


Figure 6

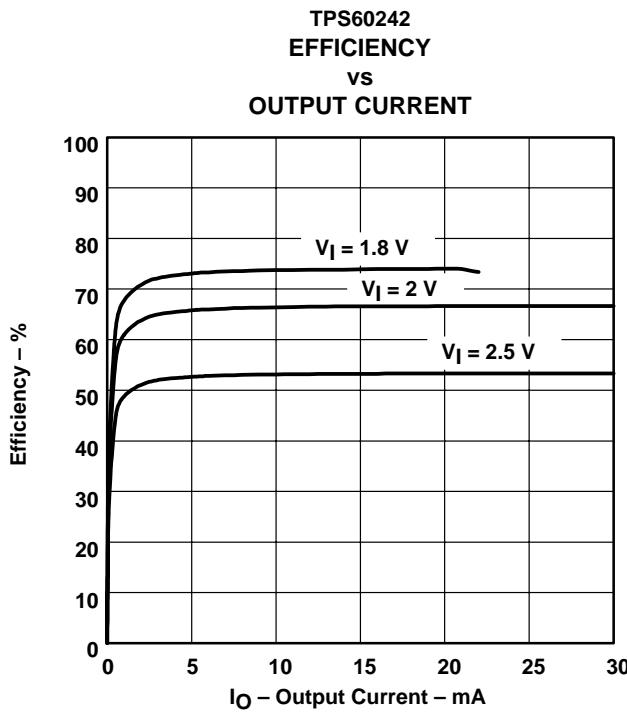


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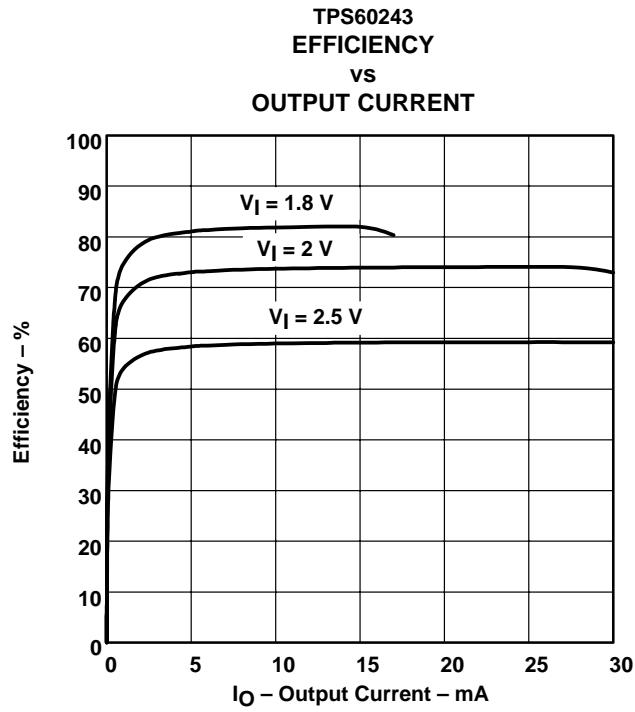


Figure 8

TYPICAL CHARACTERISTICS

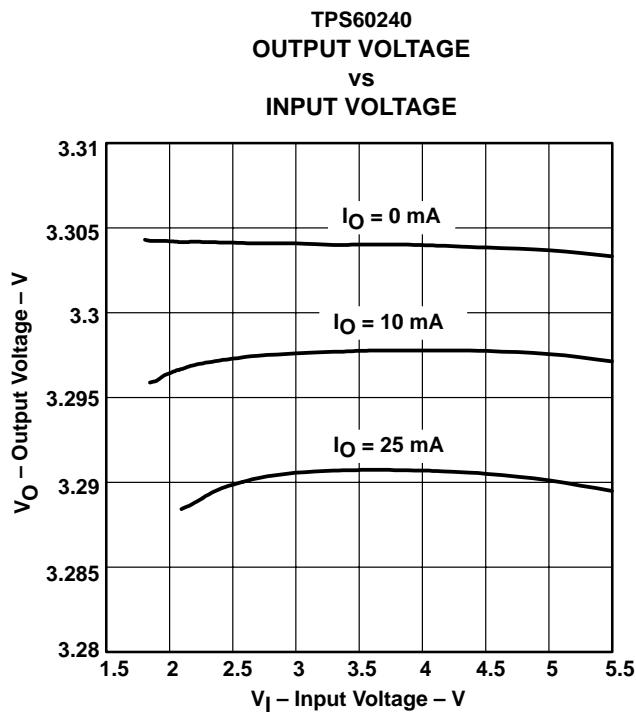


Figure 9

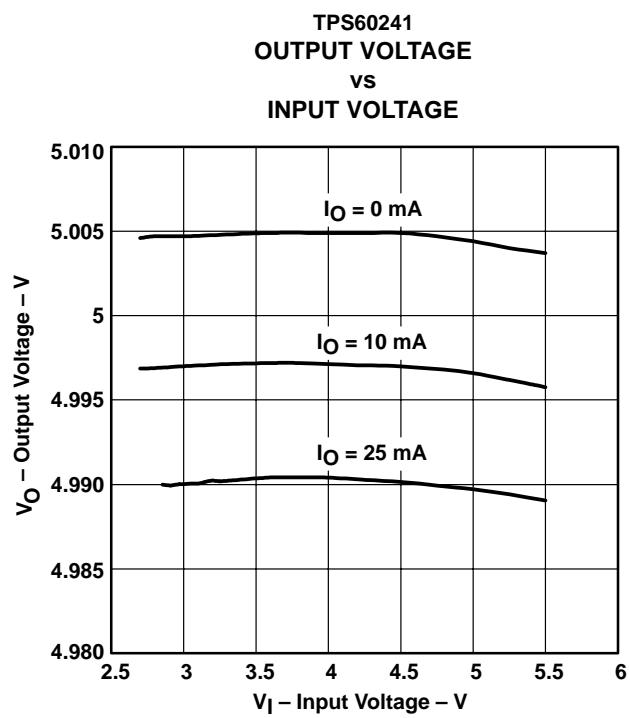


Figure 10

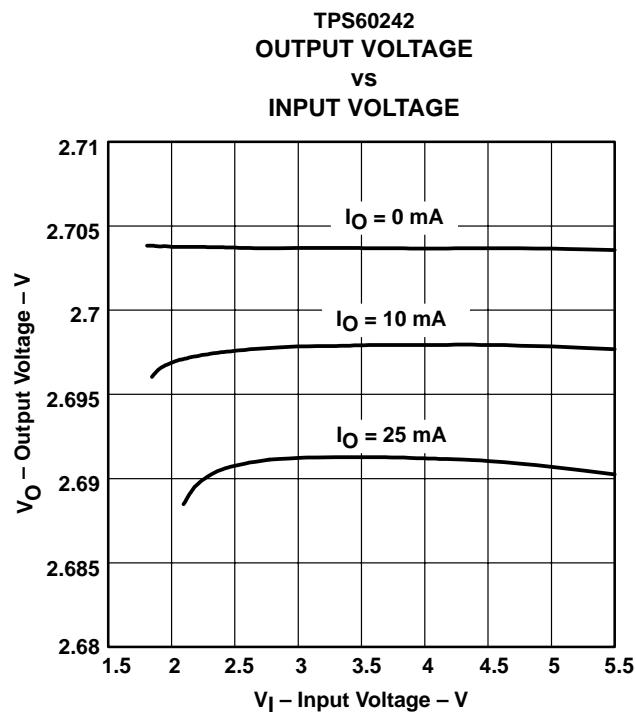


Figure 11

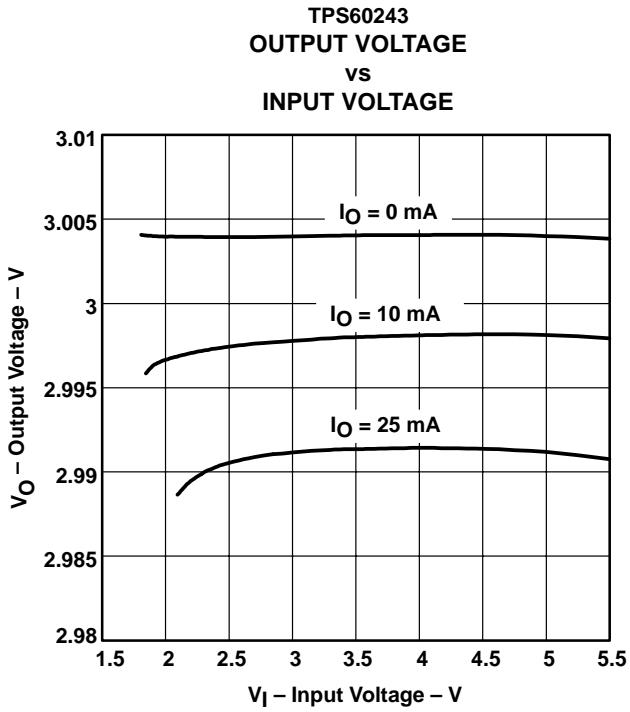
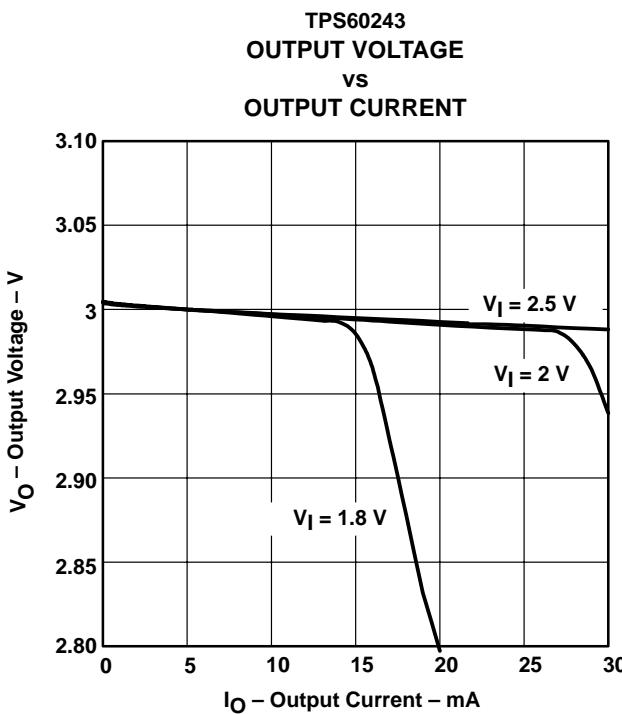
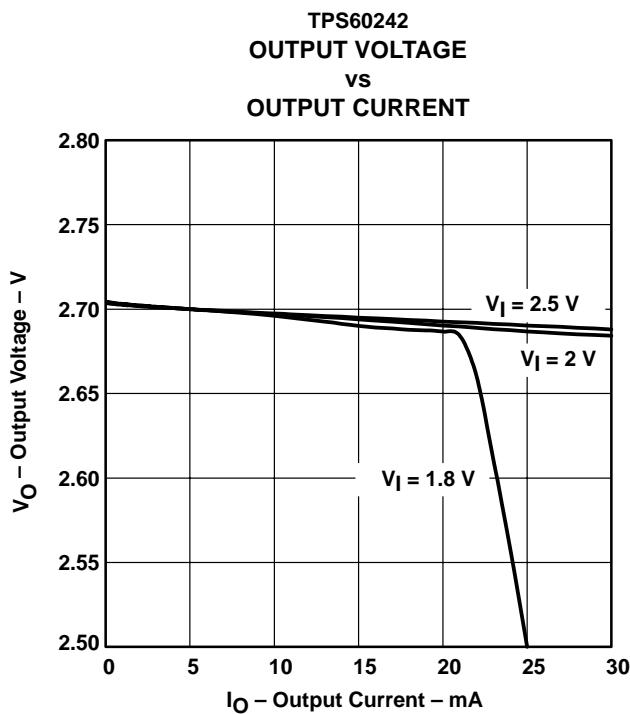
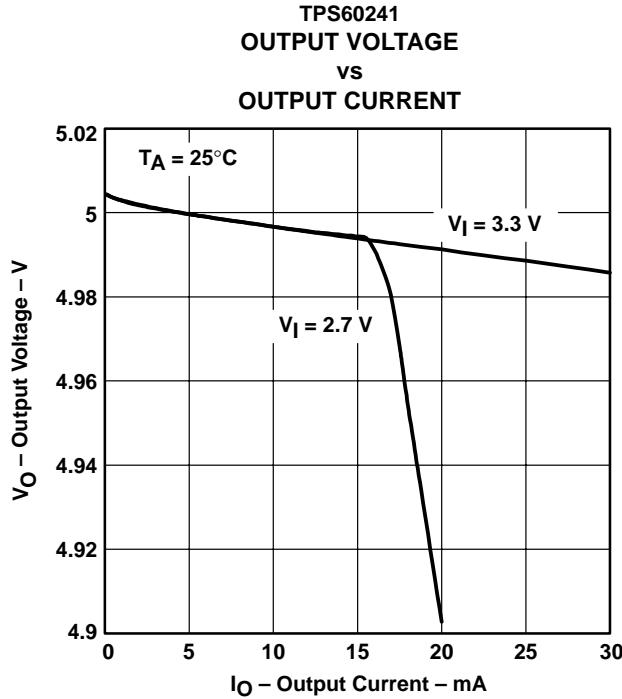
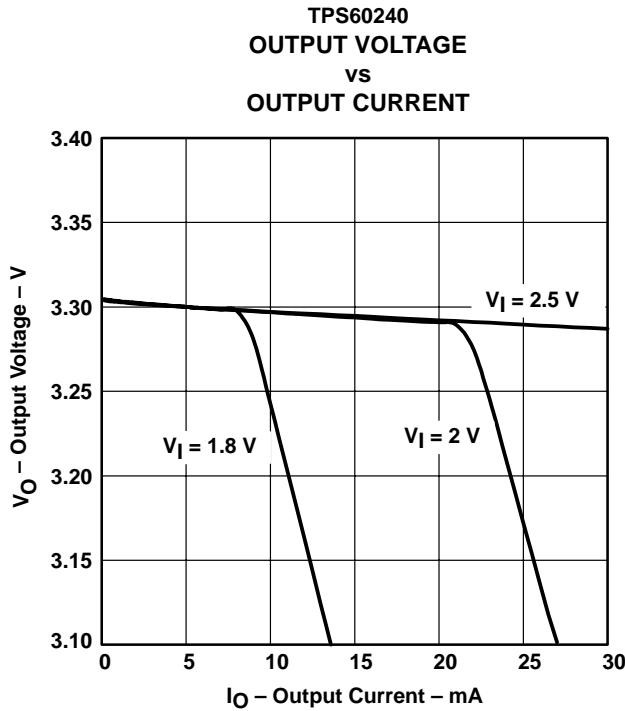


Figure 12

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS

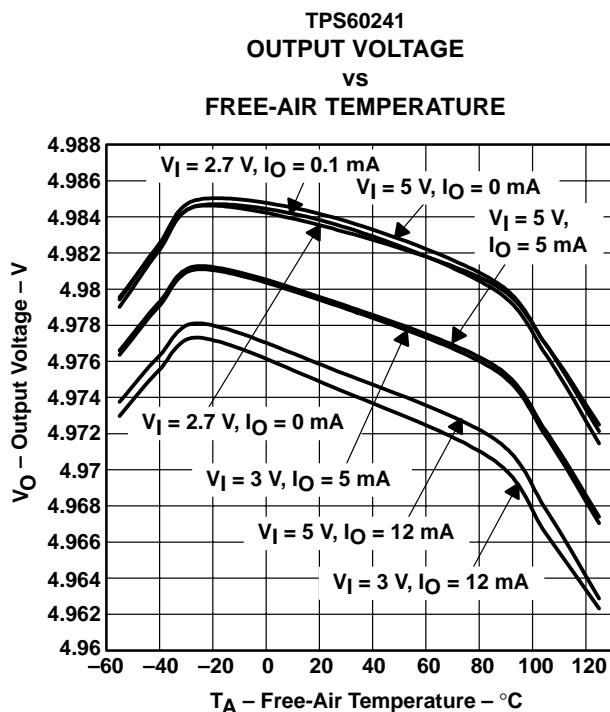


Figure 17

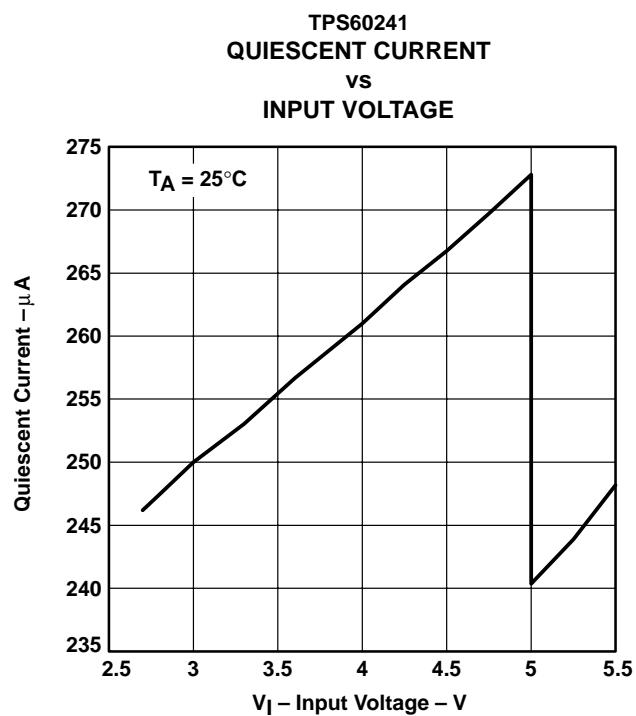


Figure 18

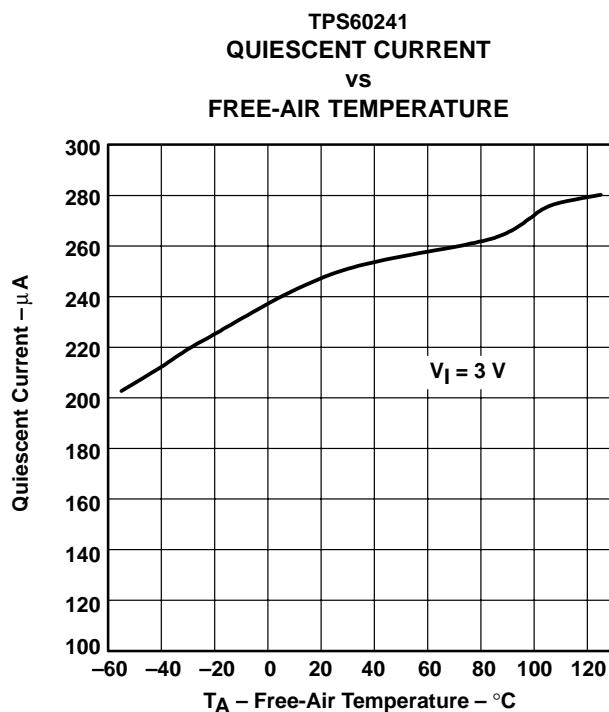


Figure 19

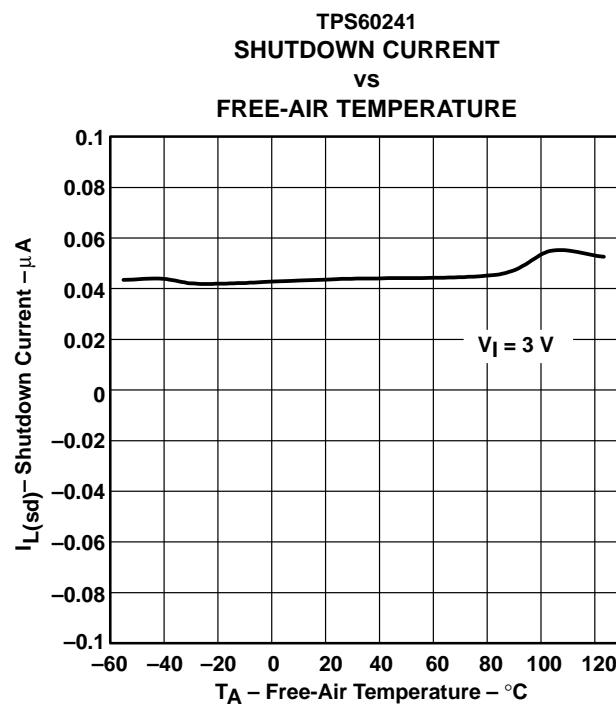
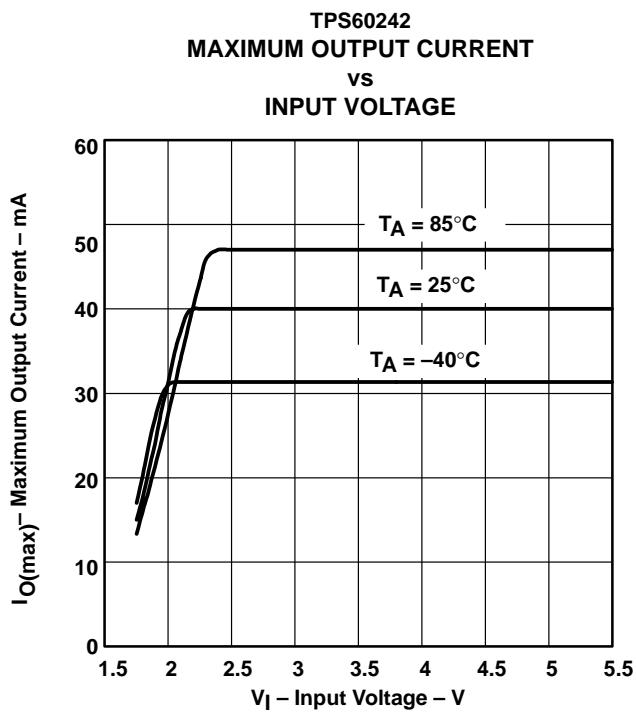
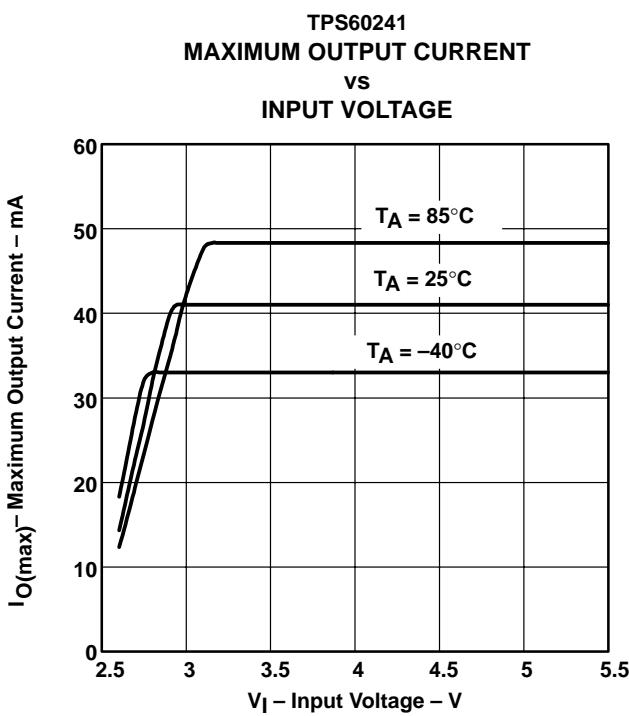
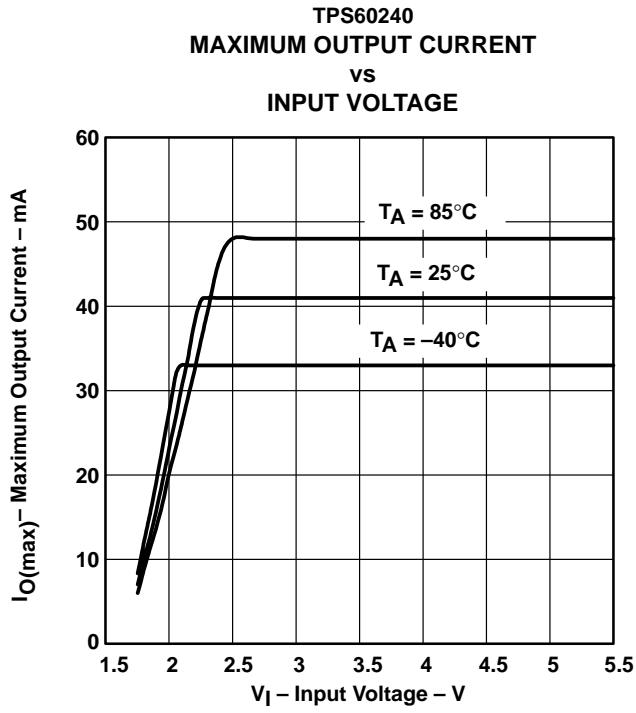
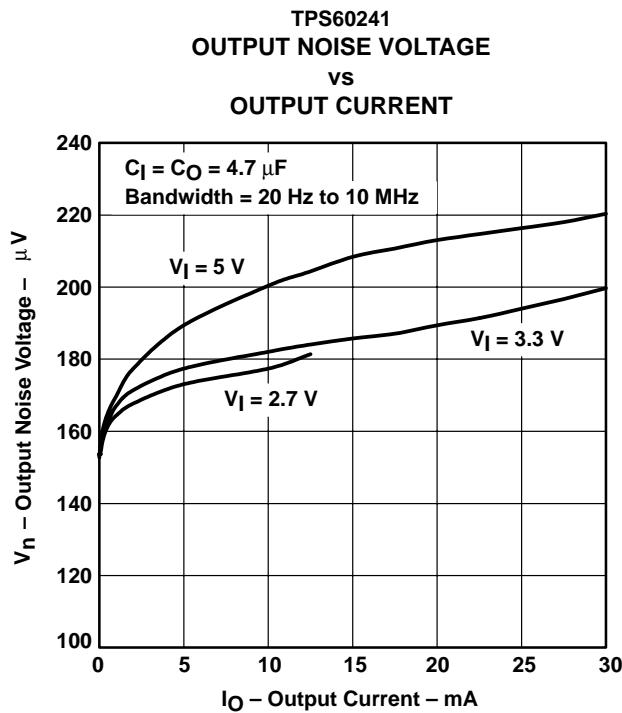


Figure 20

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS

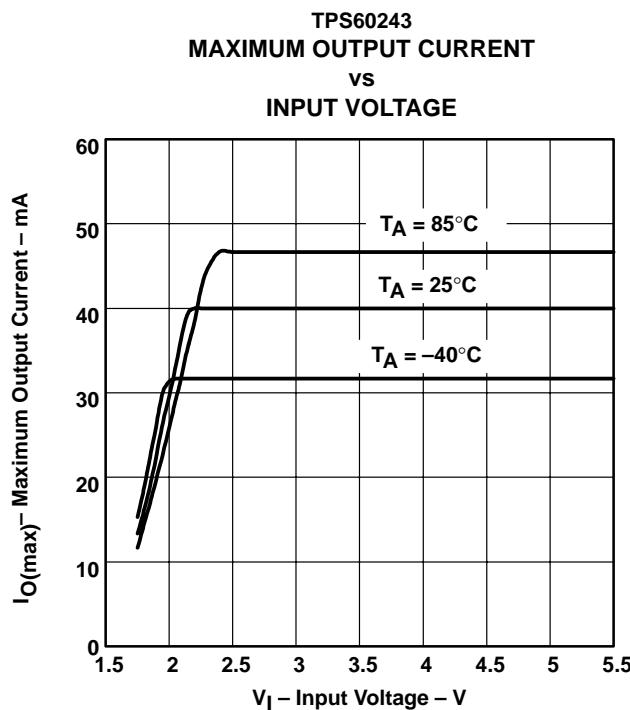


Figure 25

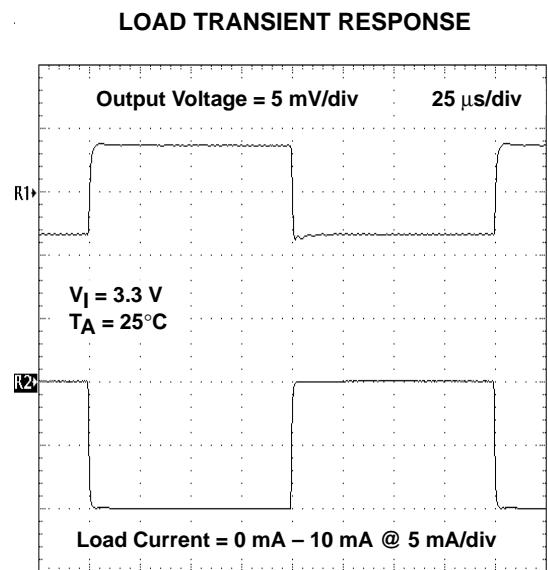


Figure 26

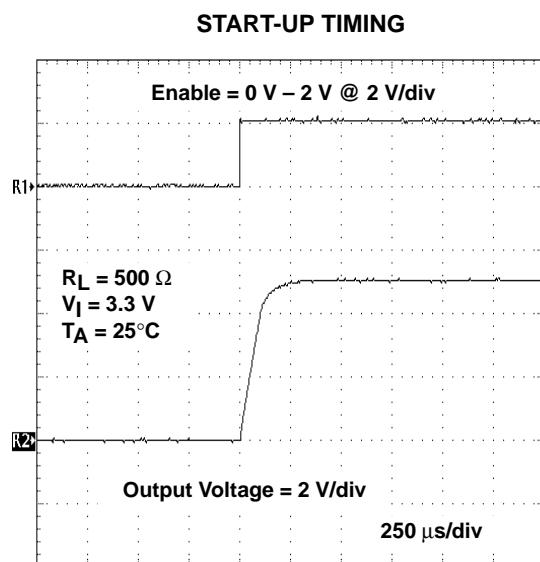


Figure 27

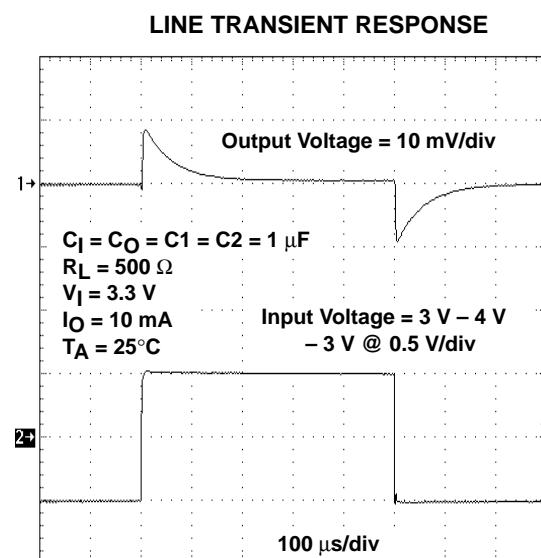


Figure 28

TYPICAL CHARACTERISTICS

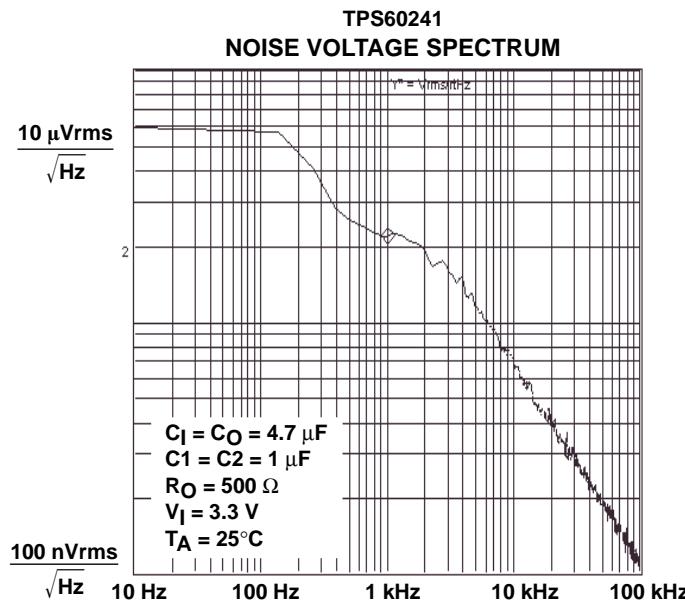
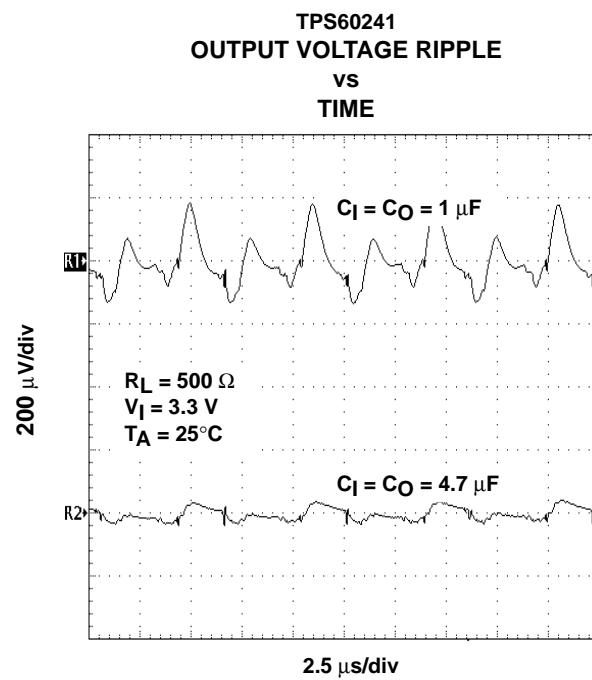


Figure 29



NOTE: Scope triggered by voltage at flying capacitors, noise removed by averaging function and bandwidth limit 20 MHz.

Figure 30

APPLICATION INFORMATION

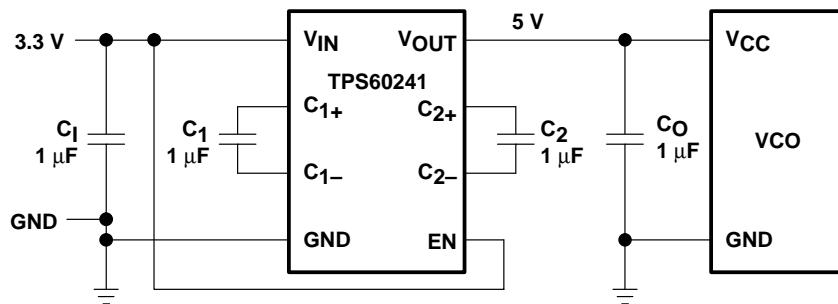


Figure 31. 5-V Low-Noise VCO Supply From 3.3-V Input

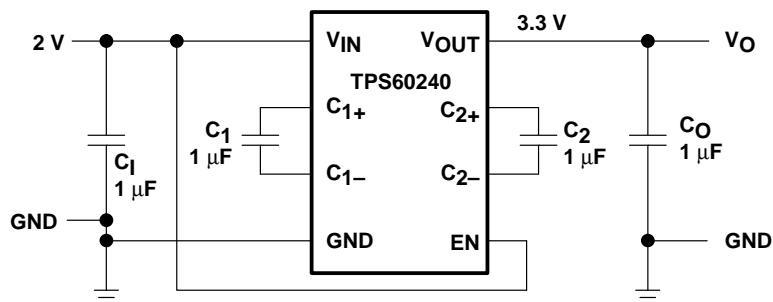


Figure 32. 2-V to 3.3-V Low-Noise Converter

output voltage ripple

The output voltage ripple depends on the capacitors used. Table 1 illustrates the dependence between output voltage ripple and capacitor selection.

Table 1. Output Voltage Ripple and Capacitor Selection

C _I	C _O	C ₁	C ₂	OUTPUT VOLTAGE RIPPLE [µVrms]
1 µF	1 µF	1 µF	1 µF	288
2.2 µF	2.2 µF	1 µF	1 µF	212
4.7 µF	4.7 µF	1 µF	1 µF	183
4.7 µF	1 µF	1 µF	1 µF	272
1 µF	4.7 µF	1 µF	1 µF	185

NOTE: V_I = 3.3 V, V_O = 5 V, R_L = 500 Ω, T_A = 25°C

APPLICATION INFORMATION

components

For the best output ripple performance, low-ESR ceramic capacitors are recommended (see Table 2).

Table 2. Recommended Capacitors

PART	MANUFACTURER	PART NUMBER	VALUE	TOLERANCE	DIELECTRIC MATERIAL	PACKAGE	RATED VOLTAGE
C _I	Taiyo Yuden	LMK212BJ105KG-T	1 μ F	10%	X7R	0805	10
	TDK	C2012X5R0J475K	4.7 μ F	10%	X5R	0805	6.3
C _O	Taiyo Yuden	LMK212BJ105KG-T	1 μ F	10%	X7R	0805	10
	TDK	C2012X5R0J475K	4.7 μ F	10%	X5R	0805	6.3
C ₁ , C ₂	Taiyo Yuden	LMK212BJ105KG-T	1 μ F	10%	X7R	0805	10
C _F	Taiyo Yuden	LMK212BJ105KG-T	1 μ F	10%	X7R	0805	10

layout consideration

In order to get optimal noise behavior, keep the power lines to the capacitors and load as short as possible. Use of power planes is recommended.

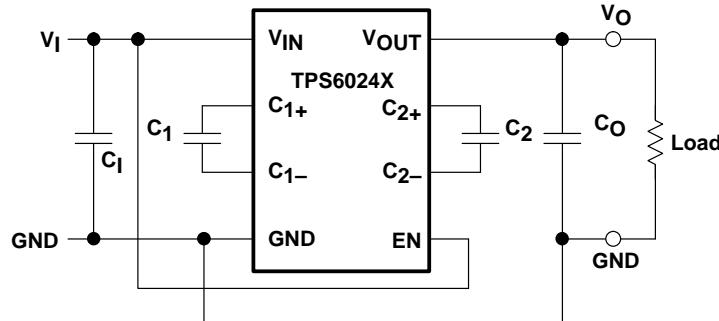


Figure 33. Layout Diagram

APPLICATION INFORMATION

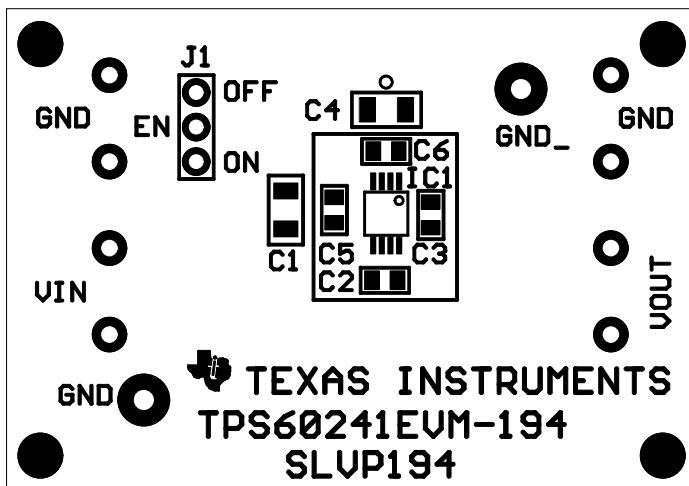


Figure 34. Top Silkscreen

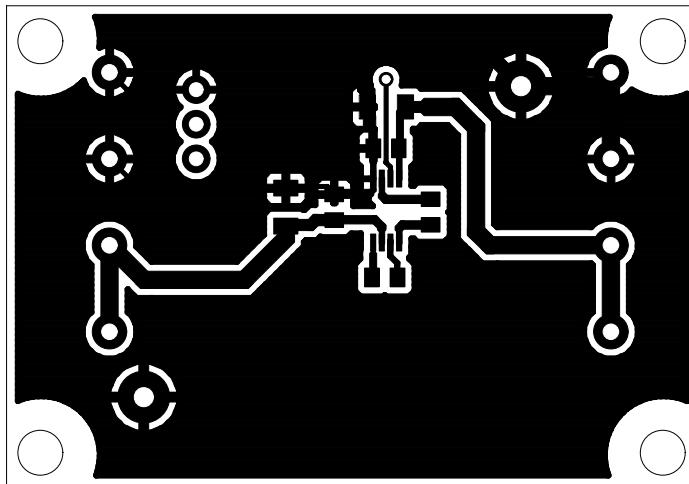


Figure 35. Top Layer

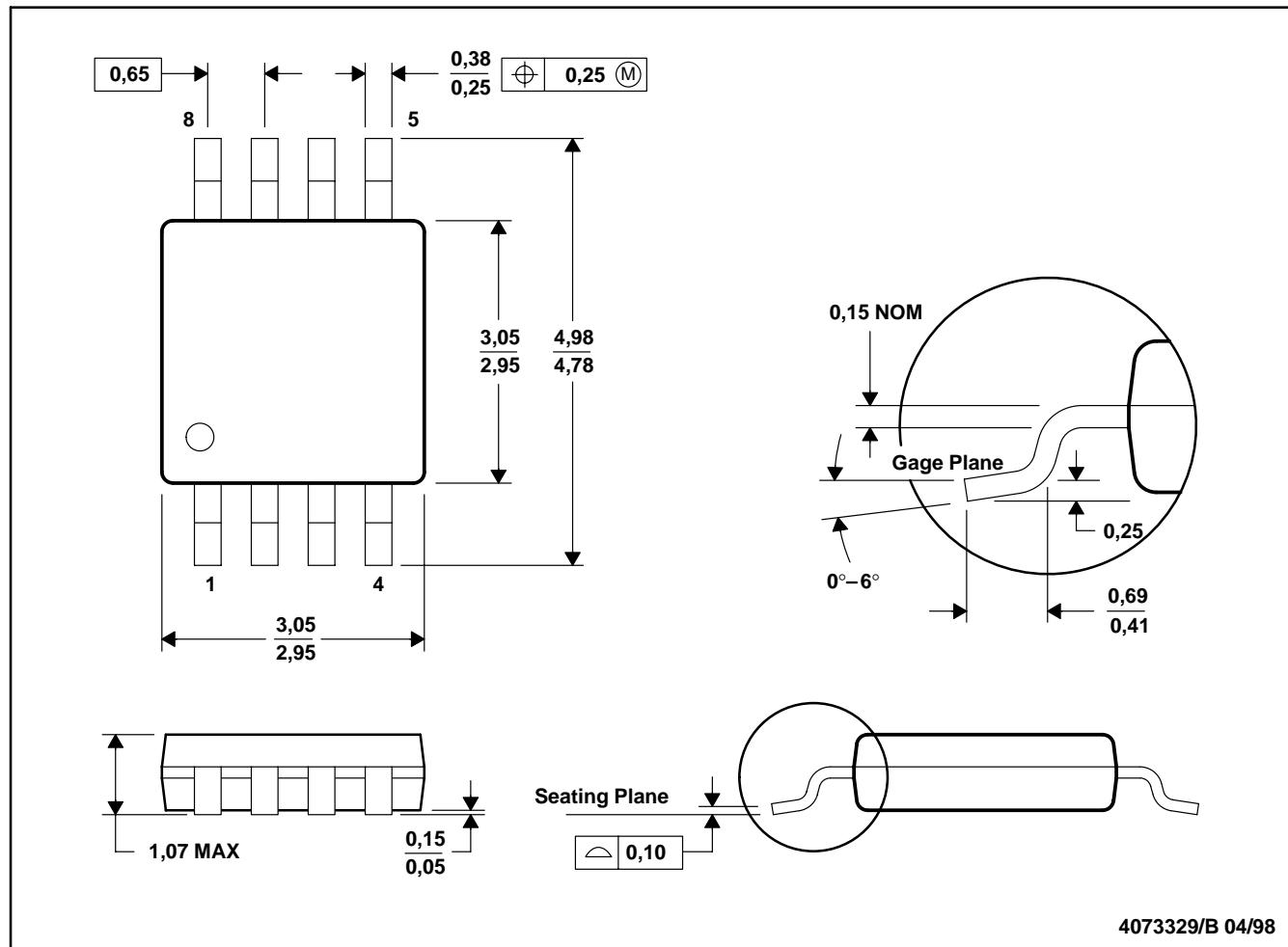
device family products

PART NUMBER	DESCRIPTION
REG710	30-mA switched cap dc/dc converter
REG711	50-mA switched cap dc/dc converter
TPS60110	Regulated 5-V, 300-mA low-noise charge pump dc/dc converter
TPS60111	Regulated 5-V, 150-mA low-noise charge pump dc/dc converter

MECHANICAL DATA

DGK (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion.
 D. Falls within JEDEC MO-187

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TPS60240DGK	OBsolete	MSOP	DGK	8		TBD	Call TI	Call TI
TPS60240DGKR	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60240DGKRG4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60240DGKT	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60240DGKTG4	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60241DGKR	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60241DGKRG4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60241DGKT	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60241DGKTG4	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60242DGK	OBsolete	MSOP	DGK	8		TBD	Call TI	Call TI
TPS60242DGKR	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60242DGKRG4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60242DGKT	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60242DGKTG4	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60243DGK	OBsolete	MSOP	DGK	8		TBD	Call TI	Call TI
TPS60243DGKR	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60243DGKRG4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60243DGKT	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
TPS60243DGKTG4	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

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⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS

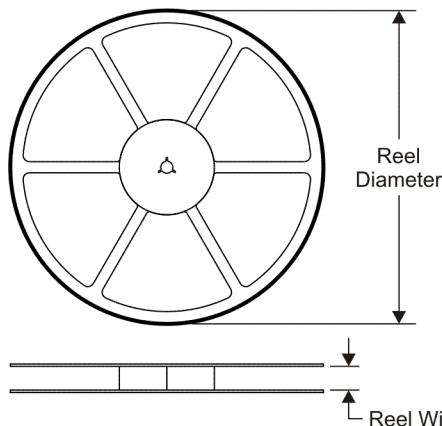
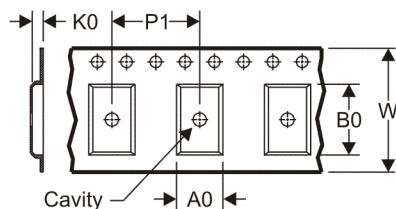
compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

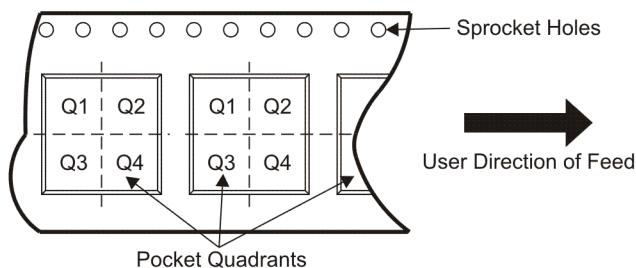
(³) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


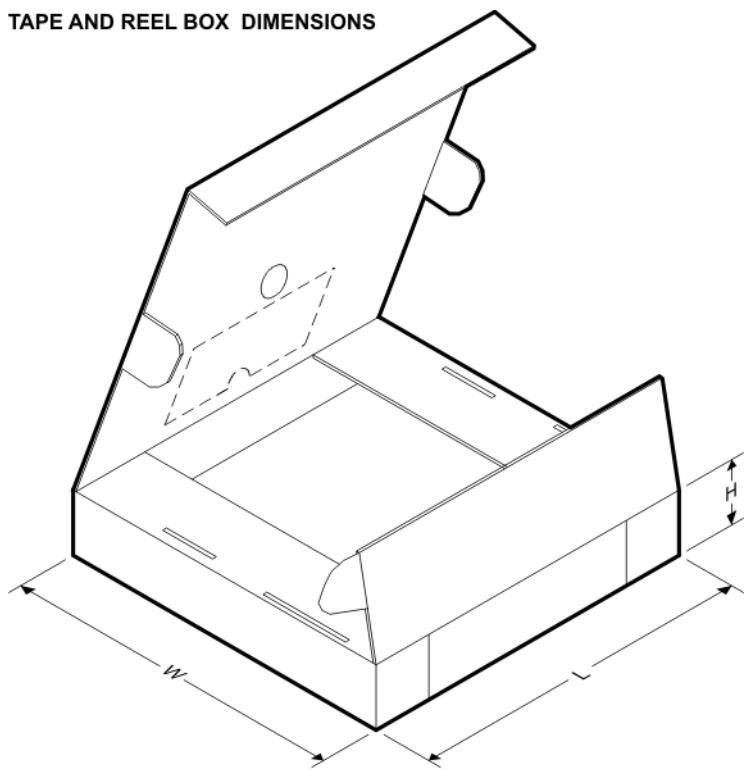
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS60240DGKR	MSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60240DGKT	MSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60241DGKR	MSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60241DGKT	MSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60242DGKR	MSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60242DGKT	MSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60243DGKR	MSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60243DGKT	MSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS60240DGKR	MSOP	DGK	8	2500	346.0	346.0	29.0
TPS60240DGKT	MSOP	DGK	8	250	190.5	212.7	31.8
TPS60241DGKR	MSOP	DGK	8	2500	346.0	346.0	29.0
TPS60241DGKT	MSOP	DGK	8	250	190.5	212.7	31.8
TPS60242DGKR	MSOP	DGK	8	2500	346.0	346.0	29.0
TPS60242DGKT	MSOP	DGK	8	250	190.5	212.7	31.8
TPS60243DGKR	MSOP	DGK	8	2500	346.0	346.0	29.0
TPS60243DGKT	MSOP	DGK	8	250	190.5	212.7	31.8

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPS60240DGK	OBsolete	VSSOP	DGK	8		TBD	Call TI	Call TI			
TPS60240DGKR	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	ATM	Samples
TPS60240DGKRG4	ACTIVE	VSSOP	DGK	8		TBD	Call TI	Call TI	-40 to 85		Samples
TPS60240DGKT	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	ATM	Samples
TPS60240DGKTG4	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	ATM	Samples
TPS60241DGKR	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AUB	Samples
TPS60241DGKRG4	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AUB	Samples
TPS60241DGKT	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AUB	Samples
TPS60241DGKTG4	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AUB	Samples
TPS60242DGK	OBsolete	VSSOP	DGK	8		TBD	Call TI	Call TI			
TPS60242DGKT	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AYF	Samples
TPS60242DGKTG4	ACTIVE	VSSOP	DGK	8		TBD	Call TI	Call TI	-40 to 85		Samples
TPS60243DGK	OBsolete	VSSOP	DGK	8		TBD	Call TI	Call TI			
TPS60243DGKR	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AYG	Samples
TPS60243DGKRG4	ACTIVE	VSSOP	DGK	8		TBD	Call TI	Call TI	-40 to 85		Samples
TPS60243DGKT	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AYG	Samples
TPS60243DGKTG4	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	AYG	Samples

(1) The marketing status values are defined as follows:

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(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

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(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

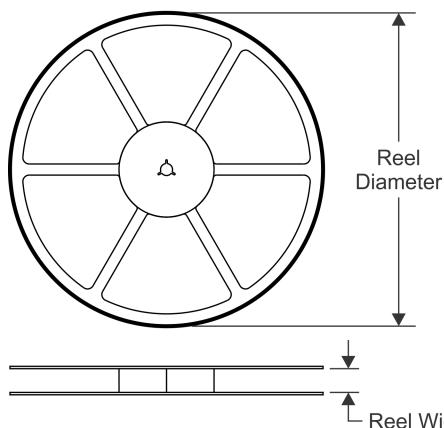
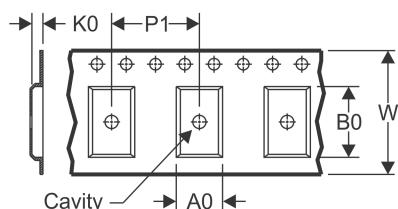
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

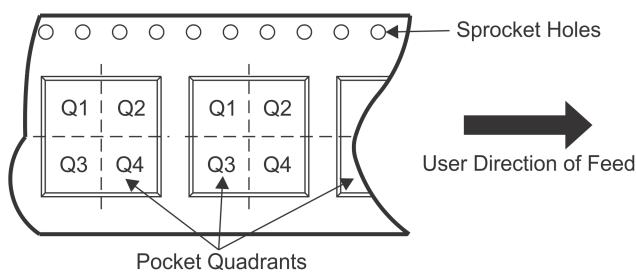
(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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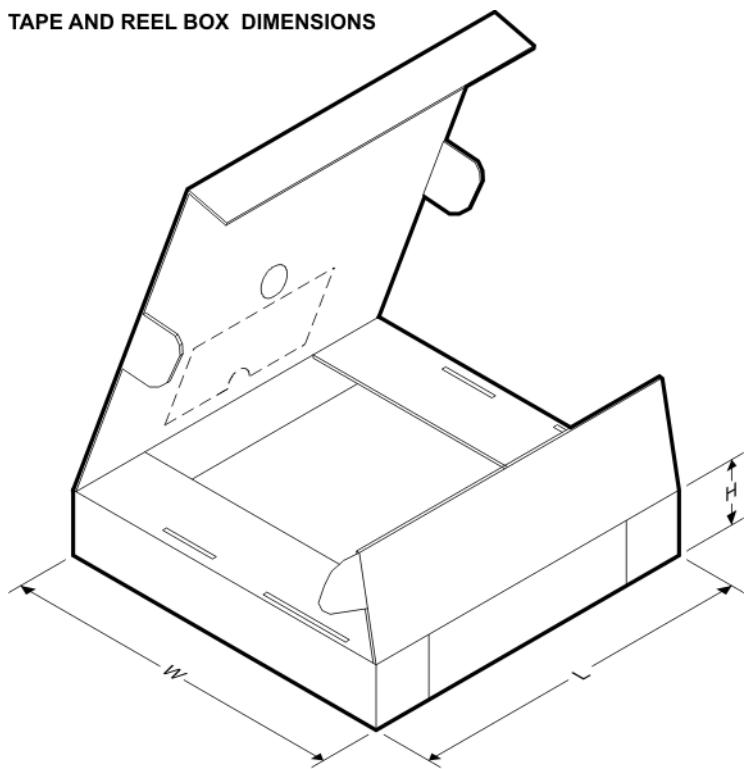
TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS60240DGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60240DGKT	VSSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60241DGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60241DGKT	VSSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60242DGKT	VSSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60243DGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60243DGKT	VSSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS60240DGKR	VSSOP	DGK	8	2500	367.0	367.0	35.0
TPS60240DGKT	VSSOP	DGK	8	250	210.0	185.0	35.0
TPS60241DGKR	VSSOP	DGK	8	2500	367.0	367.0	35.0
TPS60241DGKT	VSSOP	DGK	8	250	210.0	185.0	35.0
TPS60242DGKT	VSSOP	DGK	8	250	210.0	185.0	35.0
TPS60243DGKR	VSSOP	DGK	8	2500	367.0	367.0	35.0
TPS60243DGKT	VSSOP	DGK	8	250	210.0	185.0	35.0

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